



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application: Yeo, et al.
Serial No.: 10/078,718
Filed: February 19, 2002
For: Enhanced Chip Scale Package For Wire Bond Dies

Art Unit: 2827

Mail Stop DD
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

STATEMENT UNDER 37 CFR 1.97(E)

In accordance with 37 C.F.R. 1.97(e), counsel states that each item of information contained in the information disclosure statement dated 06 August 2003 was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of said IDS.

Enclosed please find check number 9815 in the amount of \$180.00 due under 37 CFR 1.17(p). The Commissioner is hereby authorized to charge any additional fees required for consideration of this IDS to Deposit Account 18-1167.

Respectfully submitted,

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Date: August 6, 2003

File No.: 4795-002

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CERTIFICATE OF MAILING

I HEREBY CERTIFY THAT THIS DOCUMENT IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS FIRST-CLASS MAIL, IN AN ENVELOPE ADDRESSED TO: MAIL STOP DD, COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450, ON 06 August 2003.
Name of Depositor Deborah Mondello Signature Deborah Mondello Date of Signature 8-6-03